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MOSFET - SiC Power, Single N-Channel, TO247-4L 650 V, 33 mΩ, 55 A

NTH4L045N065SC1

Features

- Typ. $R_{DS(on)} = 33 \text{ m}\Omega$ @ $V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 45 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge $(Q_{G(tot)} = 105 \text{ nC})$
- High Speed Switching with Low Capacitance (Coss = 162 pF)
- 100% Avalanche Tested
- $T_J = 175^{\circ}C$
- This Device is Pb-Free and is RoHS Compliant

Typical Applications

- SMPS (Switching Mode Power Supplies)
- Solar Inverters
- UPS (Uninterruptable Powere Supplies)
- Energy Storages

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	650	V
Gate-to-Source Voltage			V_{GS}	-8/+22	V
Recommended Operation Values of Gate-to-Source Voltage T _C < 175°C		V_{GSop}	-5/+18	٧	
Continuous Drain Current (Note 1)	Steady T 0500		I _D	55	Α
Power Dissipation (Note 1)	State	T _C = 25°C	P _D	187	W
Continuous Drain Current (Note 1)	Steady	Steady T _C = 100°C	I _D	39	Α
Power Dissipation (Note 1)	State	1C = 100 C	P _D	94	W
Pulsed Drain Current (Note 2)	T _C = 25°C		I _{DM}	197	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			Is	45	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 12 A, L = 1 mH) (Note 3)			E _{AS}	72	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			T_L	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

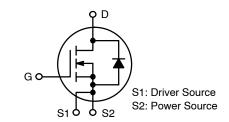
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. EAS of 72 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 12 A, V_{DD} = 50 V, V_{GS} = 18 V.



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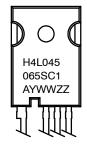
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX		
650 V	50 mΩ @ 18 V	55 A		



N-CHANNEL MOSFET



MARKING DIAGRAM



H4L045065SC1 = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTH4L045N065SC1	TO247-4L	30 Units / Tube

THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 1)	$R_{ heta JC}$	0.8	°C/W
Junction-to-Ambient - Steady State (Note 1)		40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

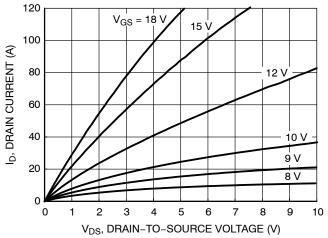
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS						ı		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		650	_	-	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 20 mA, referen	ced to 25°C	-	0.15	-	V/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V.	T _J = 25°C	-	_	10	μΑ	
		V _{GS} = 0 V, V _{DS} = 650 V	T _J = 175°C	-	-	1	mA	
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +22/-8 \text{ V}, \text{ V}$	V _{DS} = 0 V	-	_	250	nA	
ON CHARACTERISTICS (Note 2)	•					•		
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 8 mA	1.8	2.8	4.3	V	
Recommended Gate Voltage	V_{GOP}			-5	_	+18	V	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 25	A, T _J = 25°C	_	45	-	mΩ	
		V _{GS} = 18 V, I _D = 25	A, T _J = 25°C	_	33	50		
		V _{GS} = 18 V, I _D = 25 A	A, T _J = 175°C	_	41	-		
Forward Transconductance	9FS	V _{DS} = 10 V, I _D	= 25 A	_	16	-	S	
CHARGES, CAPACITANCES & GATE RESISTANCE								
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 325 V		-	1870	_	pF	
Output Capacitance	C _{OSS}			_	162	-		
Reverse Transfer Capacitance	C _{RSS}			_	14	-		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$ $I_D = 25 \text{ A}$		_	105	-	nC	
Gate-to-Source Charge	Q _{GS}			_	27	-		
Gate-to-Drain Charge	Q_{GD}			_	30	-		
Gate-Resistance	R_{G}	f = 1 MHz		-	3.1	-	Ω	
SWITCHING CHARACTERISTICS	•				•			
Turn-On Delay Time	t _{d(ON)}			-	13	_	ns	
Rise Time	t _r			-	14	-		
Turn-Off Delay Time	t _{d(OFF)}	V 5/10 V V	400 \/	-	26	_		
Fall Time	t _f	V_{GS} = -5/18 V, V_{DS} = 400 V, I_{D} = 25 A, R_{G} = 2.2 Ω inductive load		-	7	_		
Turn-On Switching Loss	E _{ON}			-	47	_	μJ	
Turn-Off Switching Loss	E _{OFF}			-	33	_		
Total Switching Loss	E _{tot}			-	80	-		
SOURCE-DRAIN DIODE CHARACTERIST		•						
Continuous Source-Drain Diode Forward Current	I _{SD}	V _{GS} = -5 V, T _J = 25°C		-	-	45	А	
Pulsed Source-Drain Diode Forward Current (Note 2)	I _{SDM}			-	-	197		
Forward Diode Voltage	V_{SD}	V _{GS} = -5 V, I _{SD} = 25 A, T _J = 25°C		-	4.4	_	V	
	•	•						

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

Parameter	Symbol Test Condition		Min	Тур	Max	Unit		
SOURCE-DRAIN DIODE CHARACTERISTICS								
Reverse Recovery Time	t _{RR}		-	20	-	ns		
Reverse Recovery Charge	Q _{RR}	V _{GS} = -5/18 V, I _{SD} = 25 A, dI _S /dt = 1000 A/μs	_	108	-	nC		
Reverse Recovery Energy	E _{REC}		_	4.5	-	μJ		
Peak Reverse Recovery Current	I _{RRM}		_	11	-	Α		
Charge time	Ta		_	11	-	ns		
Discharge time	Tb	1	-	8.5	-	ns		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V)

Figure 1. On-Region Characteristics

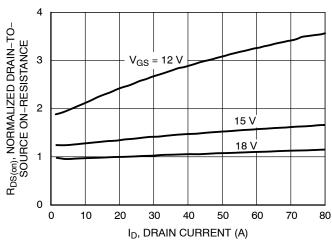


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

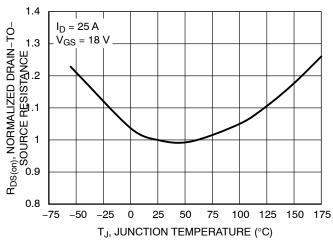


Figure 3. On–Resistance Variation with Temperature

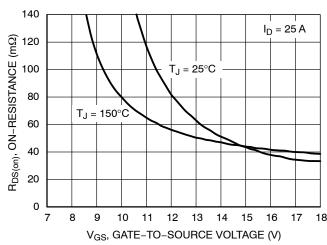


Figure 4. On-Resistance vs. Gate-to-Source Voltage

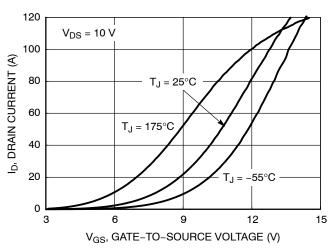


Figure 5. Transfer Characteristics

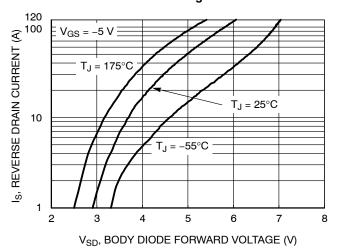


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS

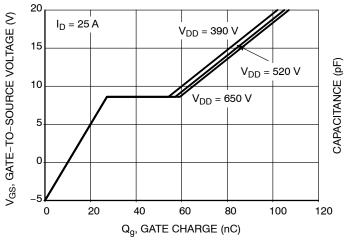


Figure 7. Gate-to-Source Voltage vs. Total Charge

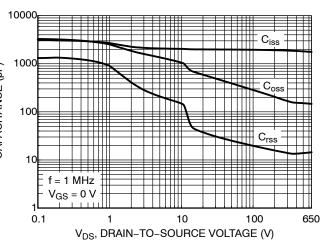


Figure 8. Capacitance vs. Drain-to-Source Voltage

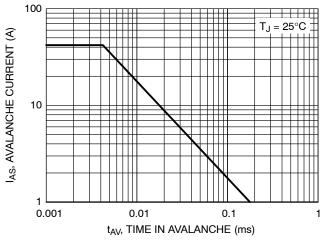


Figure 9. Unclamped Inductive Switching Capability

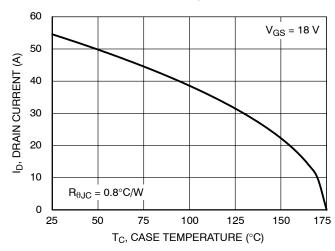


Figure 10. Maximum Continuous Drain **Current vs. Case Temperature**

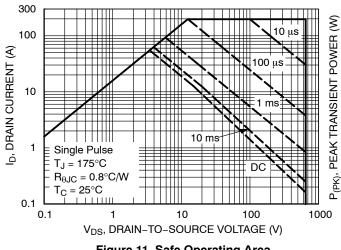


Figure 11. Safe Operating Area

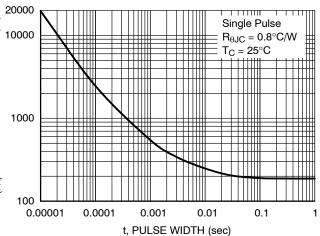


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS

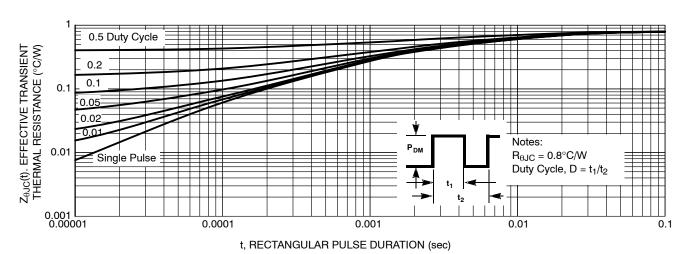
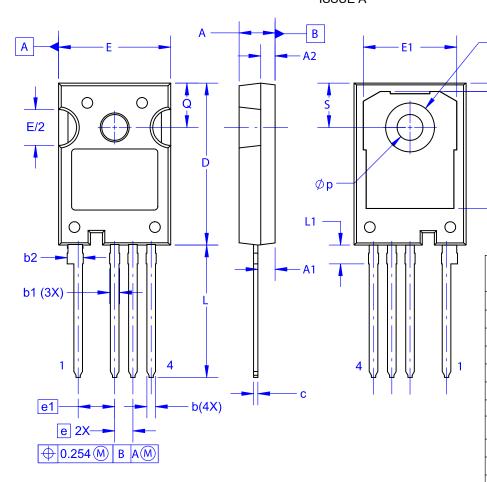


Figure 13. Junction-to-Case Thermal Response

PACKAGE DIMENSIONS

TO-247-4LD CASE 340CJ ISSUE A



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	4.80	5.00	5.20			
A1	2.10	2.40	2.70			
A2	1.80	2.00	2.20			
b	1.07	1.20	1.33			
b1	1.20	1.40	1.60			
b2	2.02	2.22	2.42			
С	0.50	0.60	0.70			
D	22.34	22.54	22.74			
D1	16.00	16.25	16.50			
D2	0.97	1.17	1.37			
е	2.54 BSC					
e1	5.08 BSC					
Е	15.40	15.60	15.80			
E1	12.80	13.00	13.20			
E/2	4.80	5.00	5.20			
L	18.22	18.42	18.62			
L1	2.42	2.62	2.82			
р	3.40	3.60	3.80			
p1	6.60	6.80	7.00			
Q	5.97	6.17	6.37			
S	5.97	6.17	6.37			

Ø**p1**

D1

- D2

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